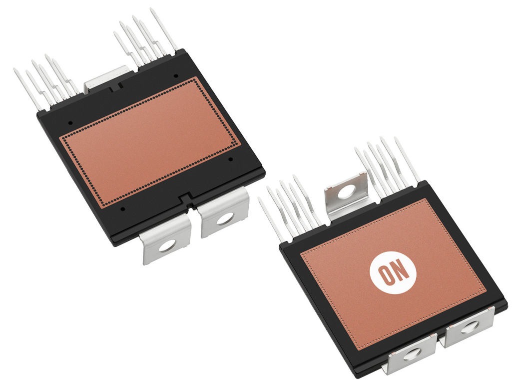
Automotive 750 V, 800 A Dual Side Cooling Half-Bridge Power Module

VE-Trac™ Dual NVG800A75L4DSC



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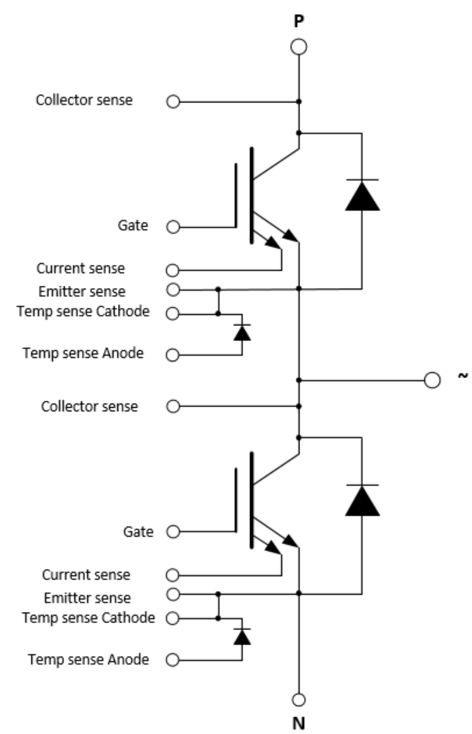


Product Description

The NVG800A75L4DSC is part of a family of power modules with dual side cooling and compact footprints for Hybrid (HEV) and Electric Vehicle (EV) traction inverter application.

The module consists of two Field Stop 4 (FS4) 750 V Narrow Mesa IGBTs in a half−bridge configuration. The chipset utilizes the new narrow mesa IGBT technology in providing high current density and robust short circuit protection with higher blocking voltage to deliver outstanding performance in EV traction applications.

Features

- Dual−Side Cooling
- Integrated Chip Level Temperature and Current Sensor
- $T_{vj\ max}$ = 175°C for Continuous Operation
- Ultra−low stray inductance
- Low V_{CESAT} and Switching Losses
- Automotive Grade FS4 & Fast Diode Chip Technologies
- 4.2 kV Isolated DBC Substrate
- AEC Qualified and PPAP Capable
- This Device is Pb−Free and is RoHS Compliant

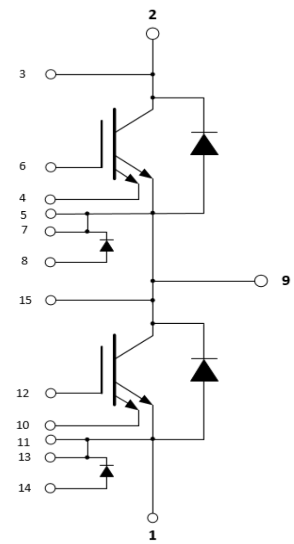
Typical Applications

- Hybrid and Electric Vehicle Traction Inverter
- High Power DC−DC Converter

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

PIN DESCRIPTION

Pin #	Pin	Pin Function Description	Pin Arrangement
1	N	Low Side Emitter	
2	P	High Side Collector	
3	H/S COLLECTOR SENSE	High Side Collector Sense	
4	H/S CURRENT SENSE	High Side Current Sense	
5	H/S EMITTER SENSE	High Side Emitter Sense	
6	H/S GATE	High Side Gate	
7	H/S TEMP SENSE (CATHODE)	High Side Temp sense Diode Cathode	
8	H/S TEMP SENSE (ANODE)	High Side Temp sense Diode Anode	
9	~	Phase Output	
10	L/S CURRENT SENSE	Low Side Current Sense	
11	L/S EMITTER SENSE	Low Side Emitter Sense	
12	L/S GATE	Low Side Gate	
13	L/S TEMP SENSE (CATHODE)	Low Side Temp sense Diode Cathode	
14	L/S TEMP SENSE (ANODE)	Low Side Temp sense Diode Anode	
15	L/S COLLECTOR SENSE	Low Side Collector Sense	

Materials

DBC Substrate: Al_2O_3 isolated substrate, basic isolation, and copper on both sides

Lead Frame: Copper with Tin electro−plating

Flammability Information

All materials present in the power module meet UL flammability rating class 94V−0

MODULE CHARACTERISTICS

Symbol	Parameter			Rating	Unit
T_{vj}	Continuous Operating Junction Temperature range			−40 to 175	°C
T_{STG}	Storage Temperature range			−40 to 125	°C
V_{ISO}	Isolation Voltage, DC, t = 1 s			4200	V
Creepage	Terminal to Terminal			6.2	mm
Clearance	Terminal to Terminal			3.4	mm
CTI	Comparative tracking index			>600	–
		Min	**Typ**	**Max**	
L_{sCE}	Stray Inductance			8	nH
$R_{CC'+EE'}$	Module lead resistance, terminals – chip			0.15	mΩ
G	Module weight			75	g
M	M4 screws for module terminals			2.2	Nm

ABSOLUTE MAXIMUM RATINGS (T_{VJ} = 25°C, Unless Otherwise Specified)

Symbol	Parameter	Rating	Unit
IGBT			
V_{CES}	Collector to Emitter Voltage	750	V
V_{GES}	Gate to Emitter Voltage	±20	V
I_{CN}	Implemented Collector Current	800	A
$I_{C\ nom}$	Continuous DC Collector Current, Tv_{Jmax} = 175°C, T_F = 65°C, ref. heatsink	550 (1)	A
I_{CRM}	Pulsed Collector Current @ VGE = 15 V, t_p = 1 ms	1600	A
Diode			
V_{RRM}	Repetitive peak reverse voltage	750	V
I_{FN}	Implemented Forward Current	800	A
I_F	Continuous Forward Current, Tv_{Jmax} = 175°C, T_F = 65°C, ref. heatsink	420 (1)	A
I_{FRM}	Repetitive Peak Forward Current, t_p = 1 ms	1600	A
I^2t value	Surge current capability, V_R = 0 V, t_p = 10 ms, Tv_J = 150°C T_{VJ} = 175°C	20000 18000	A^2s

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Verified by characterization, not by test.

THERMAL CHARACTERISTICS (Verified by characterization, not by test.)

Symbol	Parameter	Min	Typ	Max	Unit
IGBT.$R_{th,J-C}$	Effective Rth, Junction to Case (2)		0.05	0.07	°C/W
IGBT.$R_{th,J-F}$	Effective Rth, Junction to Fluid, λ_{TIM} = 6 W/m−K, F = 660 N 10 L/min, 65°C, 50/50 EGW, Ref. Heatsink		0.14		°C/W
Diode.$R_{th,J-C}$	Effective Rth, Junction to Case (2)		0.08	0.10	°C/W
Diode.$R_{th,J-F}$	Effective Rth, Junction to Fluid, λ_{TIM} = 6 W/m−K, F = 660 N 10 L/min, 65°C, 50/50 EGW, Ref. Heatsink		0.21		°C/W

2. For the measurement point of case temperature (Tc), DBC discoloration, picker circle print is allowed, please refer to the VE−Trac Dual assembly guide for additional details about acceptable DBC surface finish.

CHARACTERISTICS OF IGBT (Tvj = 25°C, Unless Otherwise Specified)

Parameters		Conditions	Min	Typ	Max	Unit
V_{CESAT}	Collector to Emitter Saturation Voltage (Terminal)	V_{GE} = 15 V, I_C = 600 A, Tv_J = 25°C Tv_J = 150°C Tv_J = 175°C V_{GE} = 15 V, I_C = 800 A, Tv_J = 25°C Tv_J = 150°C Tv_J = 175°C	–	1.30 1.42 1.45 1.44 1.64 1.68	1.55	V
I_{CES}	Collector to Emitter Leakage Current	V_{GE} = 0, V_{CE} = 750 V Tv_J = 25°C Tv_J = 175°C	– –	– 8	1 –	mA mA
I_{GES}	Gate – Emitter Leakage Current	V_{CE} = 0, V_{GE} = ± 20 V	–	–	400	nA
V_{th}	Threshold Voltage	V_{CE}= V_{GE} , I_C = 500 mA	4.6	5.5	6.2	V
Q_G	Total Gate Charge	V_{GE}= −8 to 15 V, V_{CE} = 400 V	–	1.9	–	µC
R_{Gint}	Internal gate resistance		–	2	–	Ω
C_{ies}	Input Capacitance	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	–	48	–	nF
C_{oes}	Output Capacitance	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	–	1.37	–	nF
C_{res}	Reverse Transfer Capacitance	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	–	0.15	–	nF
$T_{d.on}$	Turn on delay, inductive load	I_C = 600 A, V_{CE} = 400 V Tv_J = 25°C V_{GE} = +15/−8 V Tv_J = 150°C Rg.on = 4.7 Ω Tv_J = 175°C	–	253 283 287	–	ns
T_r	Rise time, inductive load	I_C = 600 A, V_{CE} = 400 V Tv_J = 25°C V_{GE} = +15/−8 V Tv_J = 150°C Rg.on = 4.7 Ω Tv_J = 175°C	–	94 112 117	–	ns
$T_{d.off}$	Turn off delay, inductive load	I_C = 600 A, V_{CE} = 400 V Tv_J = 25°C V_{GE} = +15/−8 V Tv_J = 150°C Rg.off = 15 Ω Tv_J = 175°C	–	760 790 800	–	ns
T_f	Fall time, inductive load	I_C= 600 A, V_{CE} = 400 V Tv_J = 25°C V_{GE} = +15/−8 V Tv_J = 150°C Rg.off = 15 Ω Tv_J = 175°C	–	95 140 153	–	ns
E_{ON}	Turn−On Switching Loss (including diode reverse recovery loss)	I_C = 600 A, V_{CE} = 400 V, V_{GE} = +15/−8 V, Ls = 20 nH, Rg.on = 4,7 Ω di/dt (Tv_J = 25°C) = 5.13 A/ns di/dt (Tv_J = 175°C) = 4.11 A/ns Tv_J = 25°C Tv_J = 150°C Tv_J = 175°C	–	22.41 33.30 36.35	–	mJ
E_{OFF}	Turn−Off Switching Loss	I_C = 600 A, V_{CE} = 400 V, V_{GE}= +15/−8 V, Ls = 20 nH, Rg.off = 15 Ω dv/dt (Tv_J = 25°C) = 2.81 V/ns dv/dt (Tv_J = 175°C) = 2.11 V/ns Tv_J = 25°C Tv_J = 150°C Tv_J = 175°C	–	27.22 37.19 39.09	–	mJ
E_{SC}	Minimum Short Circuit Energy Withstand	V_{GE} = 15 V, V_{CC} = 400 V Tv_J = 25°C Tv_J = 175°C	5 7.5			J

CHARACTERISTICS OF INVERSE DIODE (T_{VJ} = 25°C, Unless Otherwise Specified)

Parameters		Conditions		Min	Typ	Max	Unit
V_F	Diode Forward Voltage (Terminal)	V_{GE} = 0 V, I_C = 600 A,	T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C	–	1.40 1.30 1.30	1.60	V
		V_{GE} = 0 V, I_C = 800 A,	T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C		1.48 1.44 1.42		
E_{rr}	Reverse Recovery Energy	I_F = 600 A, V_R = 400 V, V_{GE} = −8 V, Rg.on = 4.7 Ω , −di/dt = 3.12 A/ns (175°C)	T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C	–	4.09 10.93 11.92	–	mJ
Q_{RR}	Recovered Charge	I_F = 600 A, V_R = 400 V, V_{GE} = −8 V, Rg.on = 4.7 Ω , −di/dt = 3.12 A/ns (175°C)	T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C	–	18.70 44.48 48.40	–	μC
Irr	Peak Reverse Recovery Current	I_F = 600 A, V_R = 400 V, V_{GE} = −8 V, Rg.on = 4.7 Ω , −di/dt = 3.12 A/ns (175°C)	T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C	–	248 331 337	–	A

SENSOR CHARACTERISTICS (T_{VJ} = 25°C, Unless Otherwise Specified)

Parameters		Conditions		Min	Typ	Max	Unit
T_{sense}	Temperature sense	I_F = 1 mA,	T_{VJ} = −40°C T_{VJ} = 25°C T_{VJ} = 150°C T_{VJ} = 175°C	2.46 (3)	2.96 2.54 1.76 1.61	2.60 (3)	V
I_{sense}	Current sense	R_{shunt} = 5 Ω	I_C = 1600 A I_C = 800 A I_C = 100 A		379 200 43.0		mV
		R_{shunt} = 20 Ω	I_C = 1600 A I_C = 800 A I_C = 100 A		644 351 94.0		

3. Measured at chip level

ORDERING INFORMATION

Part Number	Device Marking	Package	Shipping
NVG800A75L4DSC	N875DSC	AHPM15−CEA (Pb−Free)	6 Units / Tube

TYPICAL CHARACTERISTICS

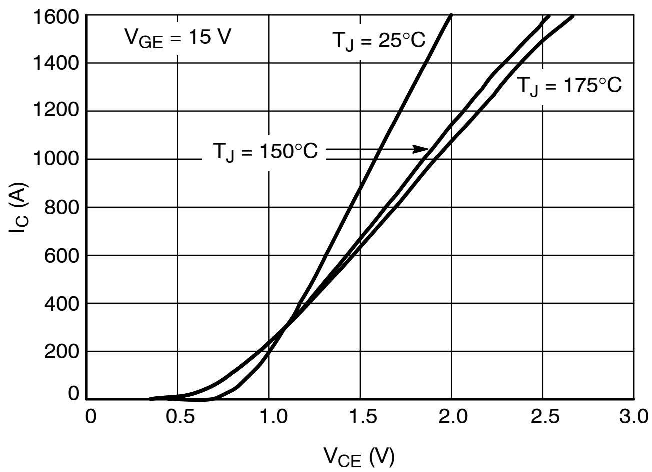


Figure 1. IGBT Output Characteristic

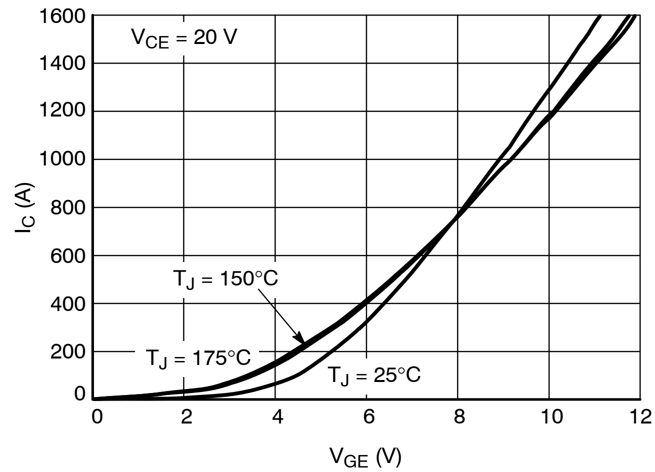


Figure 2. IGBT Output Characteristic

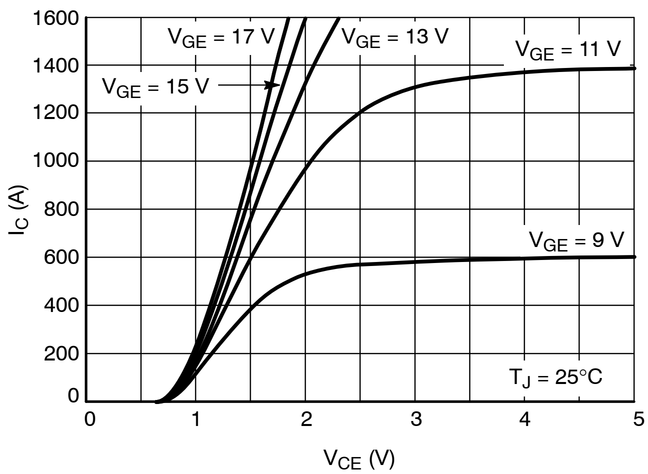


Figure 3. IGBT Output Characteristic

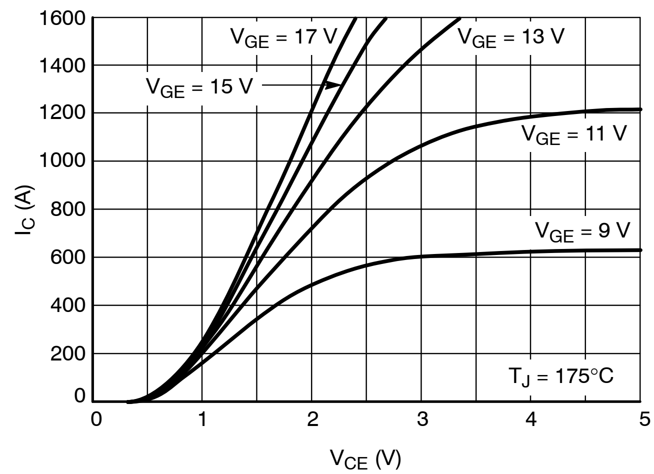


Figure 4. IGBT Output Characteristic

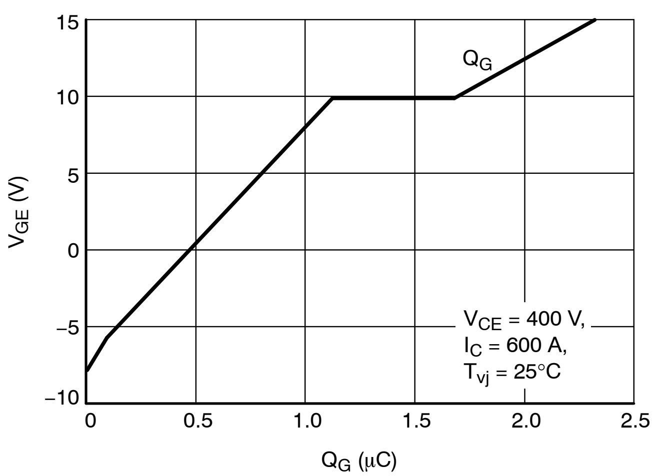


Figure 5. Gate Charge Characteristic

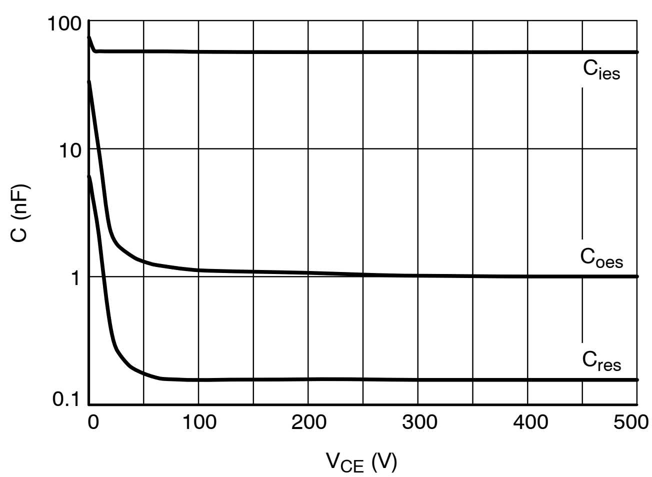


Figure 6. Capacitance Characteristic

TYPICAL CHARACTERISTICS

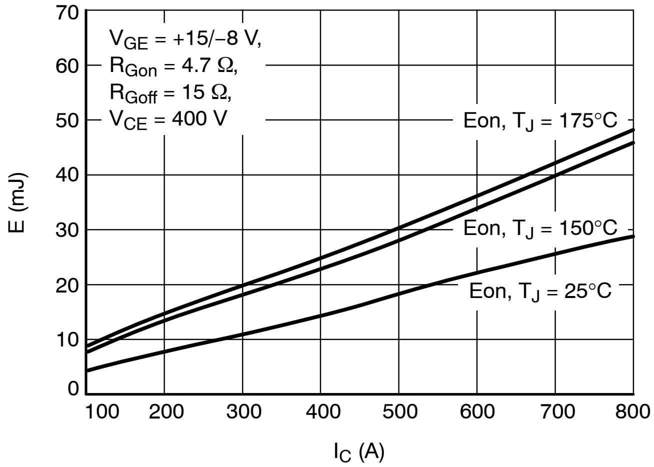


Figure 7. E_{ON} vs. I_C

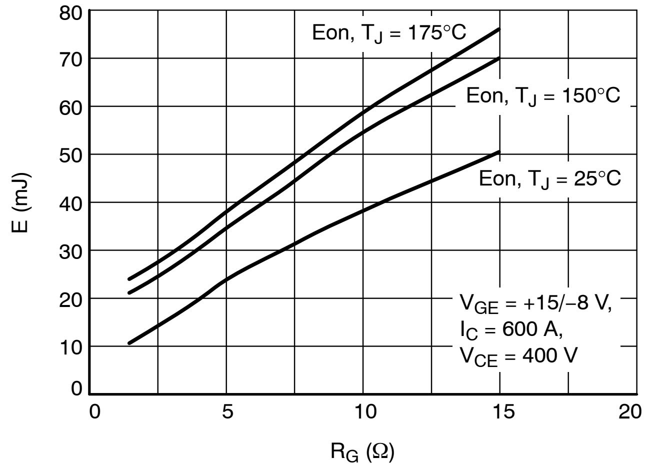


Figure 8. E_{ON} vs. R_G

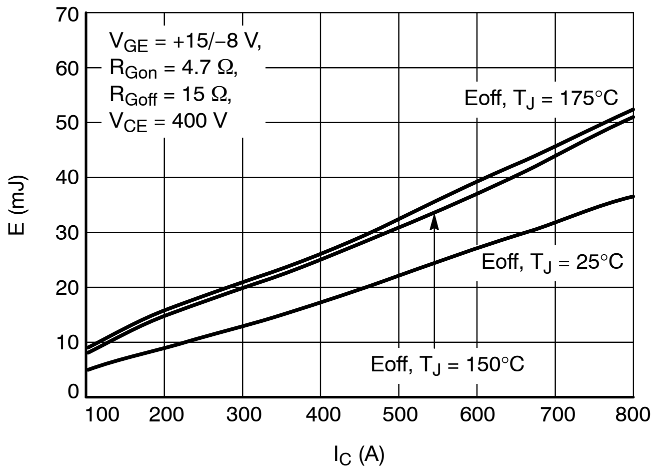


Figure 9. E_{OFF} vs. I_C

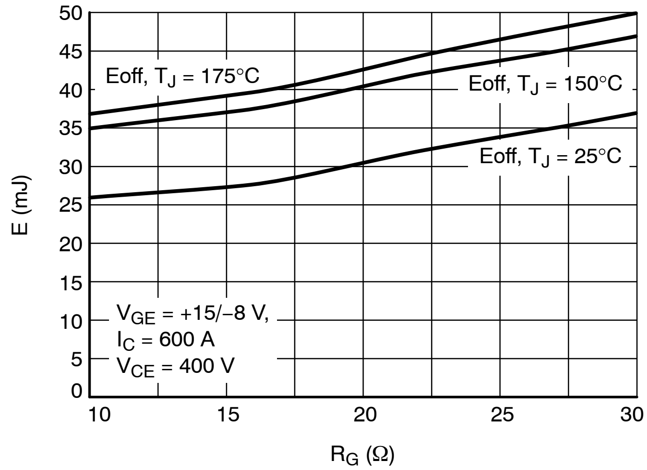


Figure 10. E_{OFF} vs. R_G

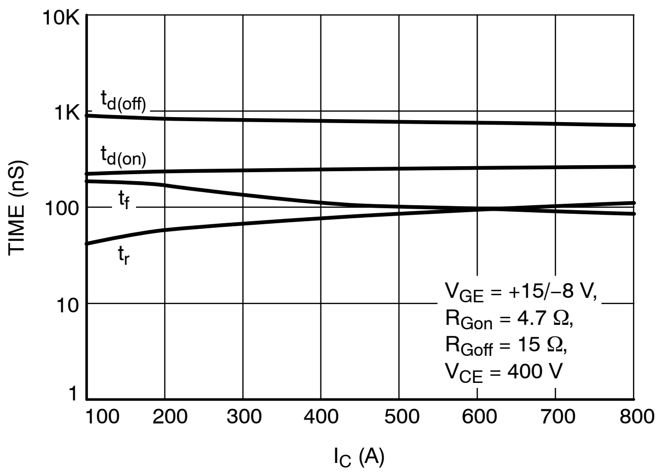


Figure 11. IGBT Switching Times vs. I_C, T_{VJ} = 25°C

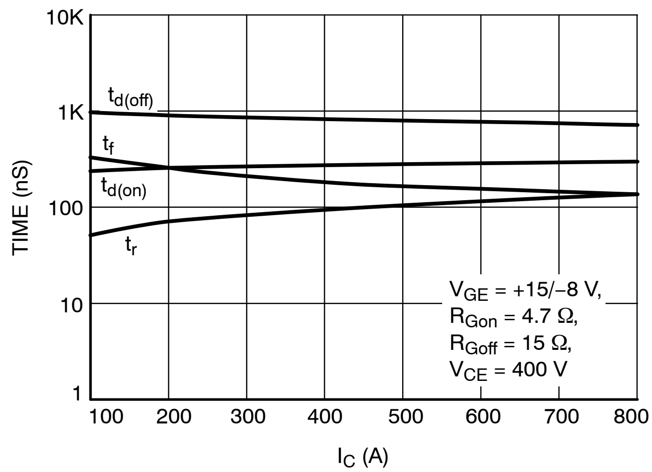


Figure 12. IGBT Switching Times vs. I_C, T_{VJ} = 175°C

TYPICAL CHARACTERISTICS

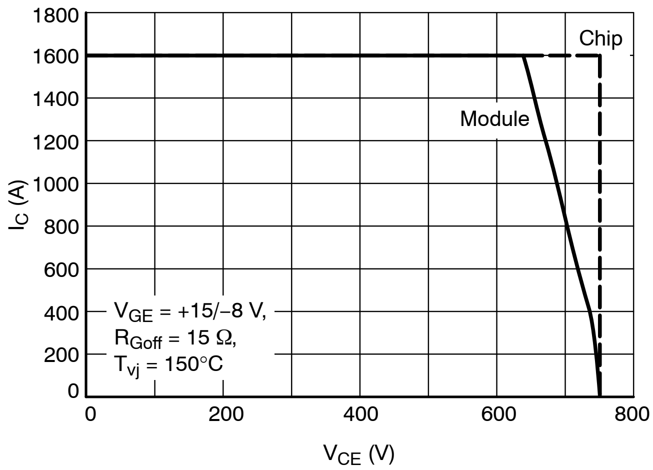


Figure 13. Reverse Bias Safe Operating Area

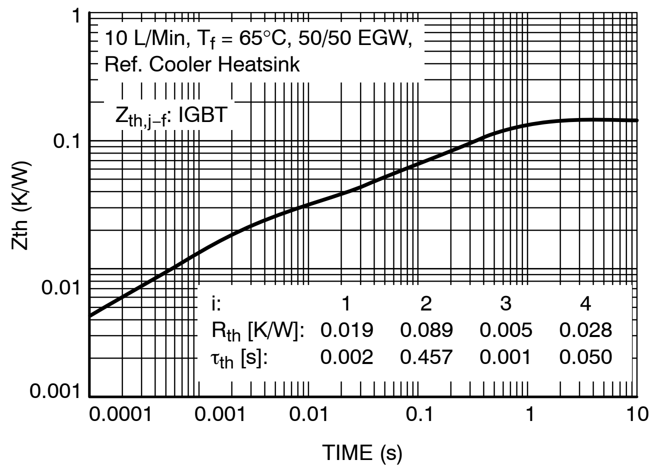


Figure 14. IGBT Transient Thermal Impedance

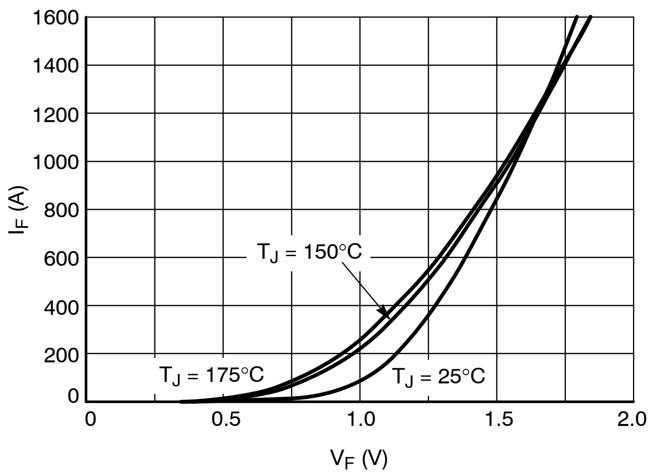


Figure 15. Diode Forward Characteristic

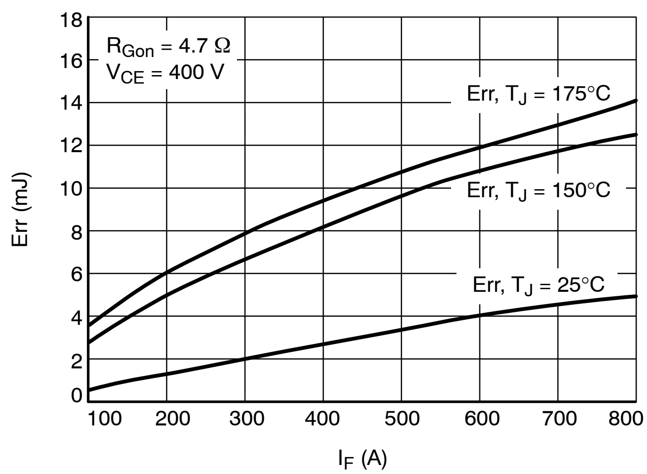


Figure 16. Diode Switching Losses vs. I_F

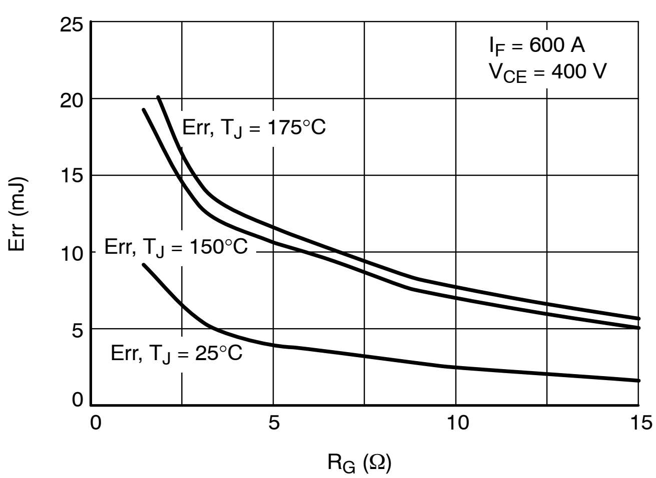


Figure 17. Diode Switching Losses vs. R_G

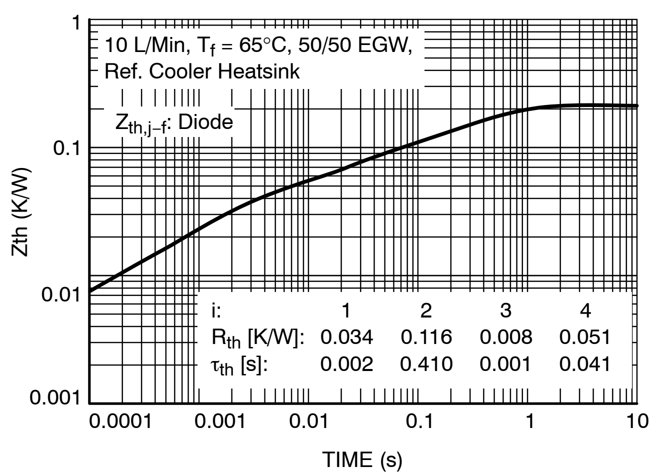


Figure 18. Diode Transient Thermal Impedance

TYPICAL CHARACTERISTICS

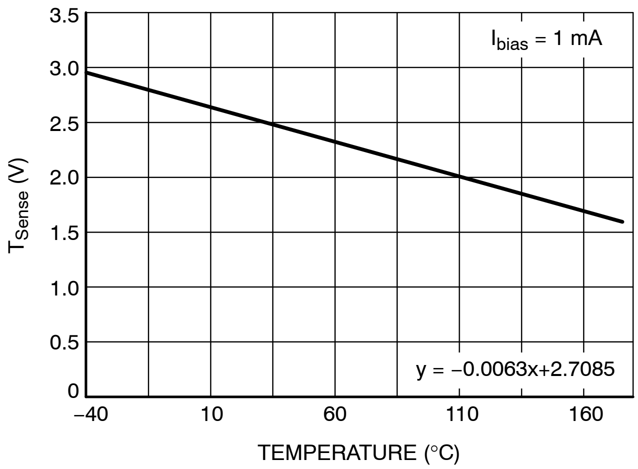


Figure 19. Temperature Sensor Characteristic

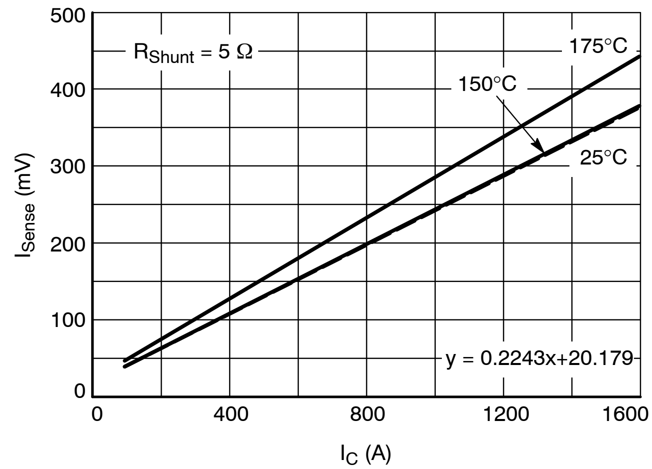


Figure 20. Current Sensor Characteristic

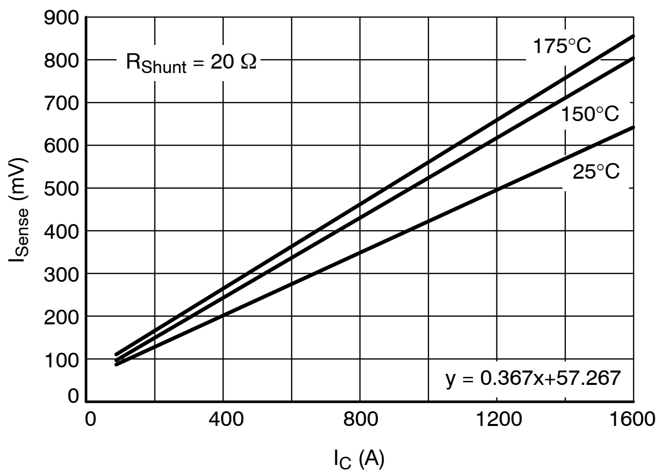


Figure 21. Current Sensor Characteristic

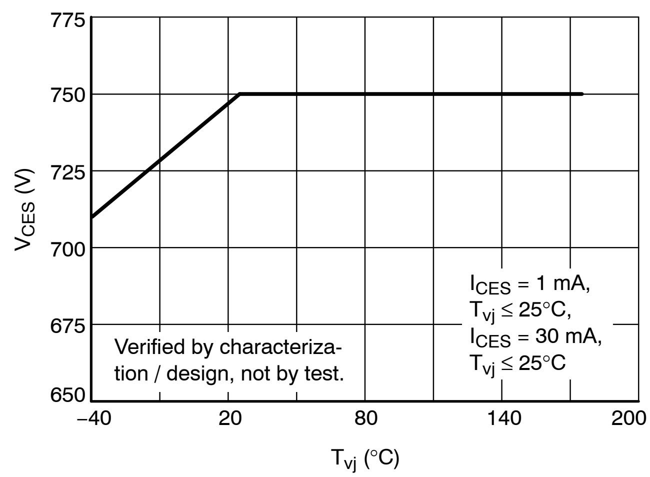


Figure 22. Maximum Allowed V_{CE}

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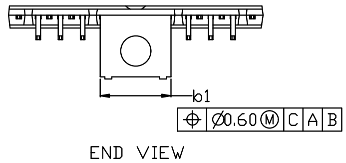
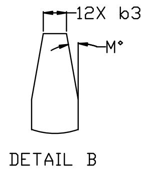
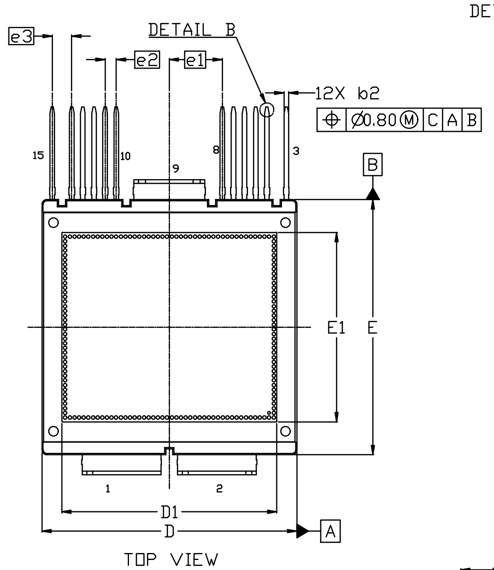
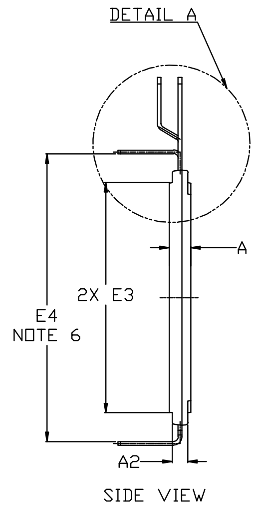
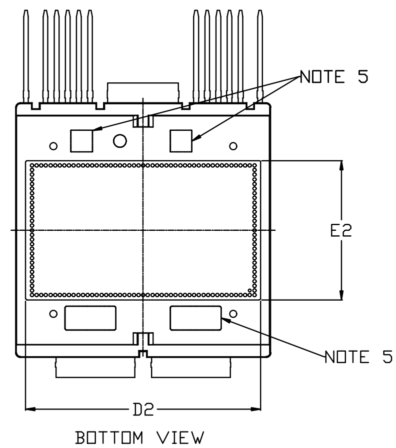


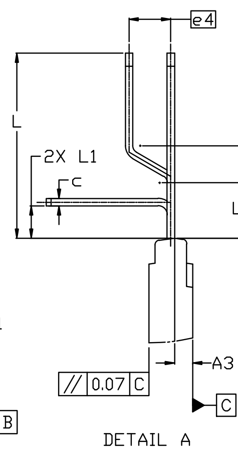


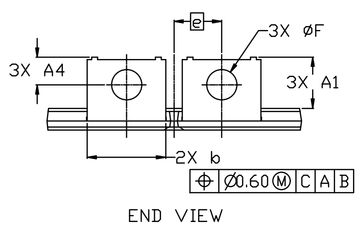
NOTES:
1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD PROTRUSIONS
4. DIMENSIONS b,b1,b2 DO NOT INCLUDE DAMBAR REMAIN.
5. MARKING AREA.
6. E4 IS FROM INNER LEAD TIP TO INNER LEAD TIP DISTANCE.







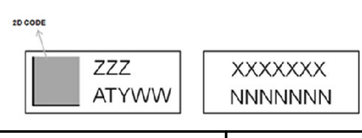




	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	4.65	4.70	4.75
A1	10.75	11.05	11.35
A2	3.20	3.40	3.60
A3	1.60	1.95	2.30
A4	5.70	6.00	6.30
b	16.90	17.00	17.10
b1	15.20	15.30	15.40
b2	0.90	1.00	1.10
b3		0.50 REF	
c	0.70	0.80	0.90
D	54.80	55.00	55.20
D1	46.20	46.50	46.80
D2	50.70	51.00	51.30

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
E	54.80	55.00	55.20
E1	40.50	40.80	41.10
E2	29.80	30.10	30.40
E3	49.40	49.60	49.80
E4	61.75	62.00	62.25
e		10.30 BSC	
e1		11.45 BSC	
e2		2.40 BSC	
e3		4.20 BSC	
e4		4.50 BSC	
F	6.45	6.50	6.55
L	19.60	20.00	20.40
L1	3.10	3.50	3.90
L2	5.70	6.00	6.30
L3	9.70	10.00	10.30
M		10° REF	

GENERIC MARKING DIAGRAM*



ZZZ = Assembly Lot Code
AT = Assembly & Test Site Code
Y = Year
WW = Work Week
XXXX = Specific Device Code
NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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onsemi Website: www.onsemi.com

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